SY58606U



4.25Gbps Precision, 1:2 CML Fanout Buffer with Internal Termination and Fail Safe Input

General Description

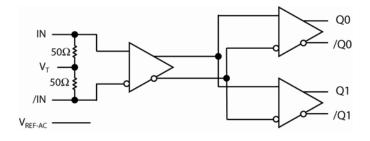
The SY58606U is a 2.5/3.3V, high-speed, fully differential 1:2 CML fanout buffer optimized to provide two identical output copies with less than 15ps of skew and less than 10ps_{pp} total jitter. The SY58606U can process clock signals as fast as 3GHz or data patterns up to 4.25Gbps.

The differential input includes Micrel's unique, 3-pin input termination architecture that interfaces to LVPECL, LVDS or CML differential signals, (AC- or DC-coupled) as small as 100mV (200mV_{pp}) without any level-shifting or termination resistor networks in the signal path. For AC-coupled input interface applications, an integrated voltage reference (V_{REF-AC}) is provided to bias the V_T pin. The outputs are 400mV CML, with extremely fast rise/fall times guaranteed to be less than 85ps.

The SY58606U operates from a 2.5V ±5% supply or 3.3V ±10% supply and is guaranteed over the full industrial temperature range (-40°C to +85°C). For applications that require LVPECL or LVDS outputs, consider Micrel's SY58607U and SY58608U, 1:2 fanout buffers with 800mV and 325mV output swings respectively. The SY58606U is part of Micrel's high-speed, Precision Edge® product line.

Datasheets and support documentation can be found on Micrel's web site at: www.micrel.com.

Functional Block Diagram





Precision Edge®

Features

- Precision 1:2, 400mV CML fanout buffer
- Guaranteed AC performance over temperature and voltage:
 - DC-to > 4.25Gbps throughput
 - <320ps propagation delay (IN-to-Q)
 - <15ps within-device skew</p>
 - <85ps rise/fall times
- Fail Safe Input
 - Prevents outputs from oscillating when input is invalid
- Ultra-low jitter design
 - <1ps_{RMS} cycle-to-cycle jitter
 - <10ps_{PP} total jitter
 - <1ps_{RMS} random jitter
 - <10ps_{PP} deterministic jitter
- High-speed CML outputs
- 2.5V ±5% or 3.3V ±10% power supply operation
- Industrial temperature range: -40°C to +85°C
- Available in 16-pin (3mm x 3mm) MLF[®] package

Applications

- Data Distribution: OC-48, OC-48+FEC, XAUI
- SONET clock and data distribution
- · Fibre Channel clock and data distribution
- Gigabit Ethernet clock and data distribution

Markets

- Storage
- ATE
- · Test and measurement
- Enterprise networking equipment
- High-end servers
- Access
- Metro area network equipment

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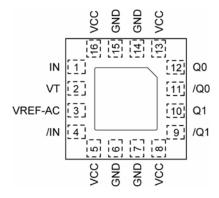
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Ordering Information⁽¹⁾

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY58606UMG	MLF-16	Industrial	606U with Pb-Free bar-line indicator	NiPdAu Pb-Free
SY58606UMGTR ⁽²⁾	MLF-16	Industrial	606U with Pb-Free bar-line indicator	NiPdAu Pb-Free

- 1. Contact factory for die availability. Dice are guaranteed at $T_A = 25$ °C, DC Electricals only.
- 2. Tape and Reel.

Pin Configuration



16-Pin MLF® (MLF-16)

Pin Description

Pin Number	Pin Name	Pin Function	
1, 4	IN, /IN	Differential Input: This input pair is the differential signal input to the device. Input accepts DC-coupled differential signals as small as 100mV (200mV _{PP}). Each pin of this pair internally terminates with 50Ω to the VT pin. If the input swing falls below a certain threshold (typical 30mV), the Fail Safe Input (FSI) feature will guarantee a stable output by latching the output to its last valid state. See "Input Interface Applications" subsection.	
2	VT	Input Termination Center-Tap: Each side of the differential input pair terminates to VT pin. This pin provides a center-tap to a termination network for maximum interface flexibility. See "Input Interface Applications" subsection.	
3	VREF-AC	Reference Voltage: This output biases to V_{CC} –1.2V. It is used for AC-coupling inputs IN and /IN. Connect VREF-AC directly to the VT pin. Bypass with 0.01 μ F low ESR capacitor to VCC. Maximum sink/source current is ±1.5mA. See "Input Interface Applications" subsection.	
5, 8,13, 16	VCC	Positive Power Supply: Bypass with 0.1uF//0.01uF low ESR capacitors as close to the V_{CC} pins as possible.	
6, 7, 14, 15	GND,	Ground: Exposed pad must be connected to a ground plane that is the same	
	Exposed pad	potential as the ground pins.	
9, 10	/Q1, Q1	CML Differential Output Pairs: Differential buffered copies of the input signal. The	
11, 12	/Q0, Q0	output swing is typically 400mV. Unused output pair may be left floating with no impact on jitter. See "CML Output Termination" subsection.	

Absolute Maximum Ratings(1)

Operating Ratings⁽²⁾

Supply voltage (V _{IN})	+2.3/5V to +3.60V
Ambient Temperature (T _A)	40°C to +85°C
Package Thermal Resistance ⁽³⁾	
$MLF^{ exttt{ iny R}}$	
Still-air (θ_{JA})	60°C/W
Junction-to-board (ψ _{JB})	33°C/W

DC Electrical Characteristics⁽⁵⁾

 $T_A = -40$ °C to +85°C, unless otherwise stated.

Symbol	Parameter	Condition	Min	Тур	Max	Units
Vcc	Power Supply Voltage Range		2.375	2.5	2.625	V
			3.0	3.3	3.6	
I _{CC}	Power Supply Current	No load, max. V _{CC}		60	77	mA
R _{DIFF_IN}	Differential Input Resistance (IN-to-/IN)		90	100	110	Ω
V _{IH}	Input HIGH Voltage (IN, /IN)	IN, /IN, Note 7	V _{CC} -1.6		V _{cc}	V
V_{IL}	Input LOW Voltage (IN, /IN)	IN, /IN	0		V _{IH} -0.1	V
V _{IN}	Input Voltage Swing (IN, /IN)	see Figure 3a, Note 6	0.1		1.7	V
V_{DIFF_IN}	Differential Input Voltage Swing (IN - /IN)	see Figure 3b	0.2			V
V _{IN_FSI}	Input Voltage Threshold that Triggers FSI			30	100	mV
V _{REF-AC}	Output Reference Voltage		V _{CC} -1.3	V _{CC} -1.2	V _{CC} -1.1	V
V_{T_IN}	Voltage from Input to V _T				1.28	V

Notes:

- 1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
- 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- 3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB. ψ_{JB} and θ_{JA} values are determined for a 4-layer board in still-air number, unless otherwise stated.
- 4. Due to the limited drive capability, use for input of the same package only.
- 5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
- V_{IN} (max) is specified when V_T is floating.
- 7. V_{IH} (min) not lower than 1.2V.

CML Outputs DC Electrical Characteristics⁽⁷⁾

 $V_{CC} = +2.5 V \pm 5\% \text{ or } +3.3 V \pm 10\%, \ R_L = 100 \Omega \text{ across the outputs; } \underline{T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \ unless otherwise stated.}$

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{OH}	Output HIGH Voltage	$R_L = 50\Omega$ to V_{CC}	V _{CC} -0.020	V _{CC} -0.010	V _{CC}	V
V _{OUT}	Output Voltage Swing	See Figure 3a	325	400		mV
V_{DIFF_OUT}	Differential Output Voltage Swing	See Figure 3b	650	800		mV
R _{OUT}	Output Source Impedance		45	50	55	Ω

Note:

^{7.} The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

AC Electrical Characteristics

 V_{CC} = +2.5V ±5% or +3.3V ±10%, R_L = 100 Ω across the outputs, Input t_r/t_f : \leq 300ps; T_A = -40°C to +85°C, unless otherwise stated.

Symbol	Parame	ter	Condition		Min	Тур	Max	Units
f _{MAX}	Maximum Frequency		NRZ Data		4.25			Gbps
			V _{OUT} > 200mV	Clock	2.5	3.0		GHz
t _{PD}	Propaga	tion Delay IN-to-Q	V _{IN} : 100mV-200mV		150	270	400	ps
			V _{IN} : 200mV-800mV		120	220	320	ps
t _{Skew}	Within Device Skew		Note 8			3	15	ps
	Part-to-Part Skew		Note 9				100	ps
t _{Jitter}	Data	Random Jitter	Note 10				1	ps _{RMS}
		Deterministic Jitter	Note 11				10	ps _{PP}
	Clock	Cycle-to-Cycle Jitter	Note 12				1	ps _{RMS}
		Total Jitter	Note 13				10	ps _{PP}
t _R t _F	Output Rise/Fall Times (20% to 80%)		At full output swing.		30	50	85	ps
	Duty Cycle		Differential I/O		47		53	%

Notes:

- 8. Within device skew is measured between two different outputs under identical input transitions.
- 9. Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and no skew at the edges at the respective inputs.
- 10. Random jitter is measured with a K28.7 pattern, measured at \leq f_{MAX}.
- 11. Deterministic jitter is measured at 2.5Gbps with both K28.5 and 2²³–1 PRBS pattern.
- 12. Cycle-to-cycle jitter definition: the variation period between adjacent cycles over a random sample of adjacent cycle pairs. t_{JITTER_CC} = T_n -T_{n+1}, where T is the time between rising edges of the output signal.
- 13. Total jitter definition: with an ideal clock input frequency of ≤ f_{MAX} (device), no more than one output edge in 10¹² output edges will deviate by more than the specified peak-to-peak jitter value.

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Functional Description

Fail-Safe Input (FSI)

The input includes a special failsafe circuit to sense the amplitude of the input signal and to latch the outputs when there is no input signal present, or when the amplitude of the input signal drops sufficiently below 100mV_{PK} (200mV_{PP}), typically 30mV_{PK}. Maximum frequency of SY58606U is limited by the FSI function.

Input Clock Failure Case

If the input clock fails to a floating, static, or extremely low signal swing, then the FSI function will eliminate a metastable condition and guarantee a stable output. No ringing and no undetermined state will occur at the output under these conditions.

Note that the FSI function will not prevent duty cycle distortion in case of a slowly deteriorating (but still toggling) input signal. Due to the FSI function, the propagation delay will depend on rise and fall time of the input signal and on its amplitude. Refer to "Typical Characteristics" for detailed information.

Timing Diagrams

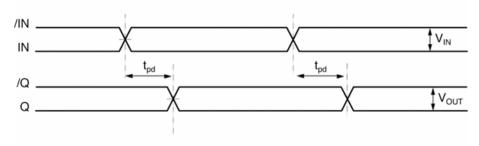


Figure 1a. Propagation Delay

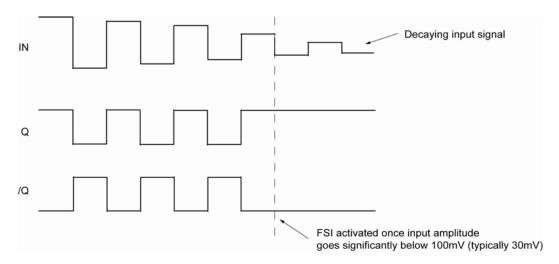
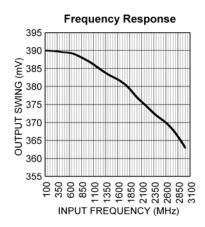
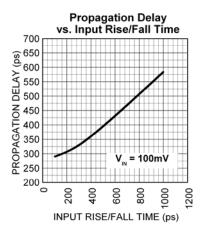


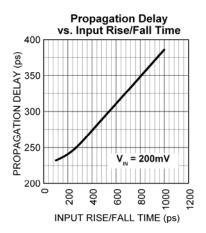
Figure 1b. Fail Safe Feature

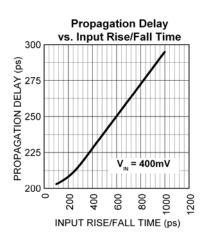
Typical Characteristics

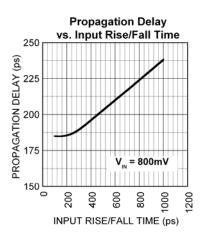
 V_{CC} = 3.3V, GND = 0V, V_{IN} = 100mV, R_L = 100 Ω across the outputs, T_A = 25°C, unless otherwise stated.





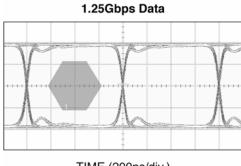




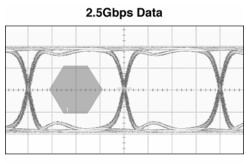


Functional Characteristics

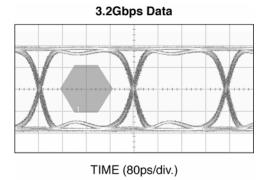
 V_{CC} = 2.5V, GND = 0V, V_{IN} = 325mV, Data Pattern: 2^{23} -1, R_L = 100 Ω across the outputs, T_A = 25°C, unless otherwise stated.

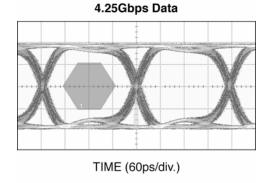


TIME (200ps/div.)



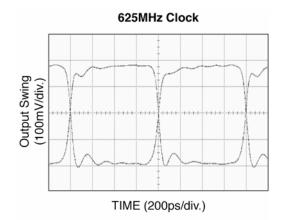
TIME (100ps/div.)

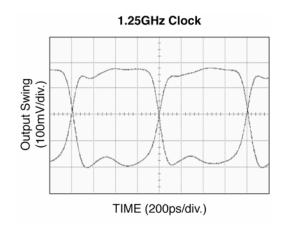


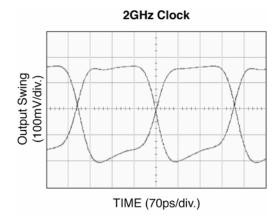


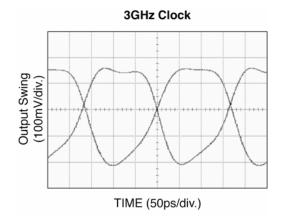
Functional Characteristics (continued)

 V_{CC} = 2.5V, GND = 0V, V_{IN} = 325mV, R_L = 100 Ω across the outputs, T_A = 25°C, unless otherwise stated.









Input and Output Stage

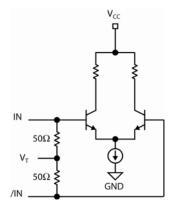


Figure 2a. Simplified Differential Input Buffer

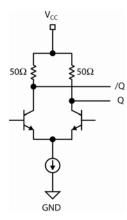


Figure 2b. Simplified CML Output Buffer

Single-Ended and Differential Swings



Figure 3a. Single-Ended Swing

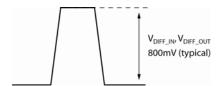


Figure 3b. Differential Swing

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Input Interface Applications

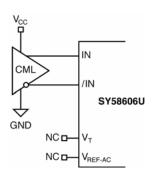


Figure 4a. CML Interface (DC-Coupled)

Option: May connect V_T to V_{CC}

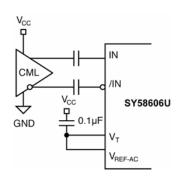


Figure 4b. CML Interface (AC-Coupled)

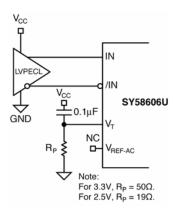


Figure 4c. LVPECL Interface (DC-Coupled)

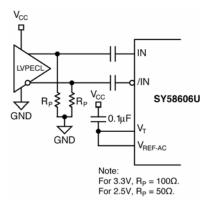


Figure 4d. LVPECL Interface (AC-Coupled)

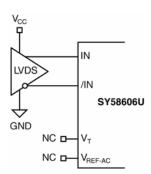
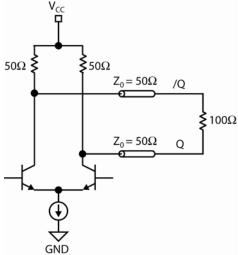


Figure 4e. LVDS Interface

CML Output Termination





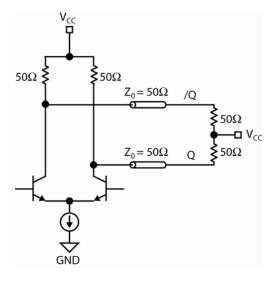


Figure 5b. CML DC-Coupled Termination

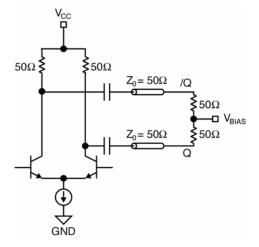


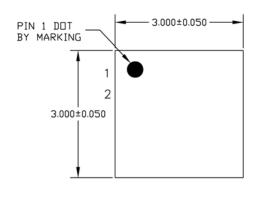
Figure 5c. CML AC-Coupled Termination

Related Product and Support Documents

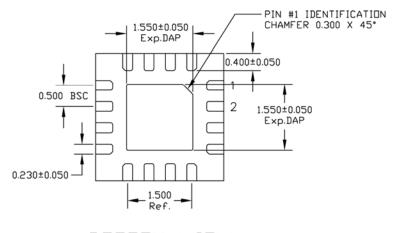
Part Number	Function	Data Sheet Link
SY58607U	3.2Gbps Precision, 1:2 LVPECL Fanout Buffer with Internal Termination and Fail Safe Input	http://www.micrel.com/page.do?page=/product-info/products/sy58607u.shtml
SY58608U	3.2Gbps Precision, 1:2 LVDS Fanout Buffer with Internal Termination and Fail Safe Input	http://www.micrel.com/page.do?page=/product-info/products/sy58608u.shtml
HBW Solutions	New Products and Termination Application Notes	http://www.micrel.com/page.do?page=/product-info/as/HBWsolutions.shtml

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Package Information



TOP VIEW

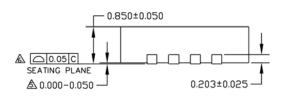


ALL DIMENSIONS ARE IN MILLIMETERS.
MAX. PACKAGE WARPAGE IS 0.05 mm.
MAXIMUM ALLOWABE BURRS IS 0.076 mm IN ALL DIRECTIONS.
PIN #1 ID ON TOP WILL BE LASER/INK MARKED.

BOTTOM VIEW

APPLIED ONLY FOR TERMINALS.

APPLIED FOR EXPOSED PAD AND TERMINALS.



SIDE VIEW

16-Pin MLF® (3mm x3mm) (MLF-16)

MICREL, INC. 2180 FORTUNE DRIVE SAN JOSE, CA 95131 USA

TEL +1 (408) 944-0800 FAX +1 (408) 474-1000 WEB http://www.micrel.com

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